# White Backlight LED Driver for Medium to Large LCD Panels (Switching Regulator Type) 

## - Description

BD6150MUV is white LED driver IC with PWM step-up DC/DC converter that can boost max 40 V and current driver that can drive max 30 mA . The wide and precision brightness can be controlled by external PWM pulse. BD6150MUV has very accurate current drivers, and it has few current errors between each strings. So, it will be helpful to reduce brightness spots on the LCD. Small package type is suited for saving space.

## - Features

1) High efficiency PWM step-up DC/DC converter (fsw $=1.25 \mathrm{MHz} / 0.75 \mathrm{MHz}$ )
2) High accuracy \& good matching current drivers (MAX30mA/ch)
3) Integrated 50 V power Nch MOSFET
4) Soft start
5) Drive up to 10 in series 6strings in parallel
6) Wide input voltage range ( $4.2 \mathrm{~V} \sim 26 \mathrm{~V}$ )
7) Rich safety functions

- Over-voltage protection
- LED terminal open/short protect - UVLO
- Over current limit
- External SBD open detect / Output short protection
- Thermal shutdown

8) Small \& thin package $($ VQFN024V4040) $4.0 \times 4.0 \times 1.0 \mathrm{~mm}$

## - Applications

All middle size LCD equipments backlight of Notebook PC, portable DVD player, car navigation systems, etc.

- Absolute maximum ratings $\left(\mathrm{Ta}=25^{\circ} \mathrm{C}\right)$

| Parameter | Symbol | Ratings | Unit | Condition |
| :--- | :---: | :---: | :---: | :--- |
| Maximum applied voltage 1 | VMAX1 | 7 | V | VREG, ISET, PWMDRV, FSEL, <br> OCPSET, VDET, TEST |
| Maximum applied voltage 2 | VMAX2 | 25 | V | LED1, LED2, LED3, <br> LED4, LED5, LED6 |
| Maximum applied voltage 3 | VMAX3 | 30.5 | V | VBAT, FAILFLAG, PWMPOW |
| Maximum applied voltage 4 | VMAX4 | 41 | V | SW |
| Power dissipation 1 | Pd1 | $500^{* 1}$ | mW |  |
| Power dissipation 2 | Pd2 | $780^{* 2}$ | mW |  |
| Power dissipation 3 | Pd3 | $1510^{* 3}$ | mW |  |
| Operating temperature range | Topr | $-40 \sim+85$ | ${ }^{\circ} \mathrm{C}$ |  |
| Storage temperature range | Tstg | $-55 \sim+150$ | ${ }^{\circ} \mathrm{C}$ |  |

[^0]- Recommended operating range $\left(\mathrm{Ta}=-40^{\circ} \mathrm{C} \sim+85^{\circ} \mathrm{C}\right)$

| Parameter | Symbol | Limits |  |  | Unit | Condition |
| :--- | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  | Min. | Typ. | Max. |  |  |
| Power supply voltage | VBAT | 4.2 | 12.0 | 26.0 | V |  |

- Electrical characteristic (Unless otherwise specified, VBAT $=12 \mathrm{~V}, \mathrm{Ta}=+25^{\circ} \mathrm{C}$ )

| Parameter | Symbol | Limits |  |  | Unit | Condition |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  | Min. | Typ. | Max. |  |  |
| Quiescent current | 19 | - | 1.6 | 4.4 | $\mu \mathrm{A}$ | PWMPOW=0V |
| Current consumption | Idd | - | 3.2 | 4.8 | mA | $\mathrm{VDET}=0 \mathrm{~V}, \mathrm{ISET}=22 \mathrm{k} \Omega$ |
| [PWMPOW Terminal] |  |  |  |  |  |  |
| Low input voltage range1 | POWL | 0 | - | 0.9 | V |  |
| High input voltage range1 | POWH | 2.1 | - | VBAT | V |  |
| Pull down resistor1 | POWR | 100 | 300 | 500 | k $\Omega$ | PWMPOW=3V |
| [PWMDRV Terminal] |  |  |  |  |  |  |
| Low input voltage range2 | PDRVL | 0 | - | 0.9 | V |  |
| High input voltage range2 | PDRVH | 2.1 | - | 5.5 | V |  |
| Pull down resistor2 | DRVR | 100 | 300 | 500 | k $\Omega$ |  |
| [FSEL Terminal] |  |  |  |  |  |  |
| Low input voltage range3 | FSL | 0 | - | 0.9 | V |  |
| High input voltage range3 | FSH | 2.1 | - | 6.0 | V |  |
| Pull down resistor3 | FSR | 100 | 300 | 500 | k $\Omega$ | FSEL=1V |
| [FAILFLAG] |  |  |  |  |  |  |
| Input resistor | FFIR | 1.0 | 2.0 | 3.0 | k $\Omega$ | FAILFLAG $=2.5 \mathrm{~V}$ |
| Off current | FFIST | - | 0.1 | 2.0 | $\mu \mathrm{A}$ | PWMPOW=0V |
| [Regulator] |  |  |  |  |  |  |
| VREG voltage | VREG | 4.2 | 5.0 | 6.0 | V | No load |
| Under voltage lock out | UVLO | 3.3 | 3.7 | 4.1 | V | VBAT falling edge |
| [Switching Regulator] |  |  |  |  |  |  |
| LED control voltage | VLED | 0.56 | 0.70 | 0.84 | V |  |
| Switching frequency | fsw | 1.00 | 1.25 | 1.50 | MHz | FSEL=L (GND short) |
| Duty cycle limit | Duty | 91 | 95.0 | 99.0 | \% | LED1-6=0.3V |
| SW Nch FET RON | RON | - | 0.48 | 0.58 | $\Omega$ | ISW=80mA |
| [Protection] |  |  |  |  |  |  |
| Over current limit | Ocp | 1.4 | 2.0 | 2.6 | A | ${ }^{* 1}$ OCPSET=68k $\Omega$ |
| OCPSET open protect | OOP | - | 0.0 | 0.1 | A | OCPSET=2M |
| Over voltage limit Input | Ovl | 0.96 | 1.00 | 1.04 | V | Detect voltage of VDET pin |
| SBD open protect | Sop | 0.02 | 0.05 | 0.08 | V | Detect voltage of VDET pin |
| VDET leak current | OVIL | - | 0.1 | 1.0 | $\mu \mathrm{A}$ |  |
| [Current driver] |  |  |  |  |  |  |
| LED maximum current | ILMAX | - | - | 30 | mA |  |
| LED current accuracy | ILACCU | - | - | $\pm 3.0$ | \% | ILED=16~20mA |
| LED current matching | ILMAT | - | - | $\pm 1.5$ | \% | Each LED current/Average (LED1-6) ILED=16~20mA |
| LED current limiter | ILOCP | - | 0 | 0.1 | mA | Current limit value at ISET resistor $1 \mathrm{k} \Omega$ setting |
| LED terminal Over voltage protect | LEDOVP | 10.0 | 11.5 | 13.0 | V | $\mathrm{PWMDRV}=2.5 \mathrm{~V}$ |
| ISET voltage | Iset | 0.5 | 0.6 | 0.7 | V |  |

[^1]
## -Reference Data



Fig 1. Quiescent Current


Fig 4. Under Voltage Lock Out


Fig 7. Max Duty


Fig 10. Over Voltage Protect


Fig 2. Current Consumption


Fig 5. ISET Voltage


Fig 8. LX NcH RON


Fig 11. SBD Open Protect


Fig 3. VREG Voltage


Fig 6. Switching Frequency


Fig 9. Over Current Limit


Fig 12. VDET Leak Current


Fig 13. LED Max Current


Fig 16. Efficiency 10LEDx6CH


Fig 14. LED Current vs LED Voltage


Fig 17. LED Current vs PWM Duty PWM Freq=200Hz LED 10x6CH


Fig 15. LED Current Matching

## -Block diagram



Fig. 18 BD6150MUV block diagram

## -Application example



Fig. 19 Application example (10LED $\times 6$ parallel, Switching frequency 750 kHz )

- Pin assignment table

| $\begin{aligned} & \hline \text { PIN } \\ & \text { No. } \end{aligned}$ | PIN Name | $\begin{aligned} & \hline \ln / \\ & \text { Out } \end{aligned}$ | Function | Terminal diagram |
| :---: | :---: | :---: | :---: | :---: |
| 1 | SW | Out | Switching Tr drive terminal | H |
| 2 | SW | Out | Switching Tr drive terminal | H |
| 3 | N.C. | - | No connect pin | F |
| 4 | PGND | - | PGND for switching Tr | D |
| 5 | FAILFLAG | Out | Fail Flag | C |
| 6 | OCPSET | In | Current Limiter setting | A |
| 7 | VDET | In | Detect input for SBD open and OVP | A |
| 8 | TEST | In | TEST signal | $J$ |
| 9 | FSEL | In | Selection of Frequency, 'L': 1.25 MHz , 'H': 0.75 MHz | J |
| 10 | ISET | In | Resister connection for LED current setting | A |
| 11 | GND | - | GND for Switching Regulator | B |
| 12 | N.C. | In | No connect pin | F |
| 13 | LED1 | In | Current sink for LED | C |
| 14 | LED2 | In | Current sink for LED | C |
| 15 | LED3 | In | Current sink for LED | C |
| 16 | LED4 | In | Current sink for LED | C |
| 17 | LED5 | In | Current sink for LED | C |
| 18 | LED6 | In | Current sink for LED | C |
| 19 | N.C. | In | No connect pin | F |
| 20 | GND | - | GND for Current driver | B |
| 21 | PWMDRV | In | PWM input pin for power ON/OFF only driver | G |
| 22 | VREG | Out | Regulator output / Internal power-supply | D |
| 23 | PWMPOW | In | PWM input pin for power ON/OFF | E |
| 24 | VBAT | In | Battery input | 1 |




B


## -Description of Functions

1) PWM current mode DC/DC converter

While this IC is power ON, the lowest voltage of LED terms is detected, PWM duty is decided to be 0.7 V and output voltage is kept invariably. As for the inputs of the PWM comparator as the feature of the PWM current mode, one is overlapped with error components from the error amplifier, and the other is overlapped with a current sense signal that controls the inductor current into Slope waveform to prevent sub harmonic oscillation. This output controls internal Nch Tr via the RS latch. In the period where internal Nch Tr gate is ON, energy is accumulated in the external inductor, and in the period where internal Nch Tr gate is OFF, energy is transferred to the output capacitor via external SBD. This IC has many safety functions, and their detection signals stop switching operation at once.
2) Soft start

This IC has soft start function.
The soft start function prevents large coil current.
Rush current at turning on is prevented by the soft start function.
After PWMPOW, PWMDRV is changed $L \rightarrow H$, soft start becomes effective for within 4 ms and soft start doesn't become effective even if PWMPOW is changed $L \rightarrow H$ after that.
And, when the H section of PWMPOW is within 4 ms , soft start becomes invalid when PWMPOW is input to H more than three times. The invalid of the soft start can be canceled by making PWMPOW, PWMDRV $\rightarrow \mathrm{L}$.


Fig. 20 Soft start


Fig. 21 Soft start reset and set
3) FAILFLAG

When the error condition occurs, boost operating is stopped by the protection function, and the error condition is outputted from FAILFLAG. After power ON, when the protection function is operating under about 1 ms have passed.

Object of protect function is as shown below.

- Over-voltage protection
- External SBD open detect/ Output Short protection
- LED terminal open/short protection
- Over current limit


Fig. 22 FAILFLAG operating description

## -Protection

- Over voltage protection

At such an error of output open as the output DC/DC and the LED is not connected to IC, the DC/DC will boost too much and the VDET terminal exceed the absolute maximum ratings, and may destruct the IC. Therefore, when VDET becomes sensing voltage or higher, the over voltage limit works, and turns off the output Tr , and the pressure up made stop. At this moment, the IC changes from activation into non-activation, and the output voltage goes down slowly. And, when the Feedback of LED1 isn't returned, so that Vout will return normal voltage.


Fig. 23 VDET operating description

- External SBD open detect / Output short protection In the case of external SBD is not connected to IC, or VOUT is shorted to GND, the coil or internal Tr may be destructed. Therefore, at such an error as VDET becoming 0.05 V or below, and turns off the output Tr , and prevents the coil and the IC from being destructed.
And the IC changes from activation into non-activation, and current does not flow to the coil ( 0 mA ).
- Thermal shut down

This IC has thermal shut down function.
The thermal shut down works at $175^{\circ} \mathrm{C}$ or higher, and the IC changes from activation into non-activation.

## -How to set over voltage limit

This section is especially mentioned here because the spec shown electrical characteristic is necessary to explain this section.

Over voltage limit
LED control voltage
LED terminal over voltage protect

```
min 0.96V typ 1.00V max 1.04V
min 0.56V typ 0.70V max 0.84V
min 10.0V typ 11.5 V max 13.0V
```

1. Calculate the conditions that the total value of LED VF is MAX.

Example) In the case of serial 8 LEDs with $\mathrm{VF}=2.9 \mathrm{~V}(\min ), 3.2 \mathrm{~V}(\operatorname{tgp}), 3.5 \mathrm{~V}(\max )=>3.5 \mathrm{~V} \times 8=28 \mathrm{~V}$
2. Then calculate the biggest value of output with the following formula.

The biggest value of output = the biggest value calculated for $1+$ the biggest value of LED terminal voltage. $(0.84 \mathrm{~V})$ Example) The biggest value of output $=28 \mathrm{~V}+0.84 \mathrm{~V}=28.84 \mathrm{~V}$
3. Set the smallest value of over voltage larger than the biggest value of output.

If over voltage is closer to the total value of VF, it could be occurred to detect over voltage by ripple, noise, and so on.
It is recommended that some margins should be left on the difference between over voltage and the total value of VF. This time around 6\% margin is placed.
Example) Against the biggest value of output $=28.84 \mathrm{~V}$, the smallest value of over voltage $=28.84 \mathrm{~V} \times 1.06=30.57 \mathrm{~V}$ Ic over voltage limit $\min =0.96 \mathrm{~V}, \mathrm{typ}=1.00 \mathrm{~V}, \max =1.04 \mathrm{~V}$
typ $=30.57 \mathrm{~V} \times(1.00 \mathrm{~V} / 0.96 \mathrm{~V})=31.8 \mathrm{~V}$
$\max =31.8 \mathrm{~V} \times(1.04 \mathrm{~V} / 1.00 \mathrm{~V})=33.1 \mathrm{~V}$
4. The below shows how to control resistor setting over voltage

Please fix resistor $2.2 \mathrm{M} \Omega$ between VDET and output and then set over voltage after changing resistor between VDET and GND. While PWM is off, output voltage decreases by minimizing this resistor. Due to the decrease of output voltage, ripple of output voltage increases, and singing of output condenser also becomes bigger.
Example) Selecting OVP resistor.
(Example 1) VF=3.6V max, serial $=7$ LED
$\mathrm{OVP}=1.0 \mathrm{~V}, \mathrm{R} 1=2.2 \mathrm{M} \Omega, \mathrm{R} 2=78.7 \mathrm{k} \Omega$
$\mathrm{VOUT}=1.0 \times(2.2 \mathrm{M} \Omega+78.7 \mathrm{k} \Omega) / 78.7 \mathrm{k} \Omega=28.95 \mathrm{~V}$
(Example 2) $\mathrm{VF}=3.6 \mathrm{~V}$ max, serial $=8$ LED
$\mathrm{OVP}=1.0 \mathrm{~V}, \mathrm{R} 1=2.2 \mathrm{M} \Omega, \mathrm{R} 2=69.8 \mathrm{k} \Omega$
VOUT $=1.0 \times(2.2 \mathrm{M} \Omega+69.8 \mathrm{k} \Omega) / 69.8 \mathrm{k} \Omega=32.52$
(Example 3) VF=3.6V max, serial $=9$ LED
$\mathrm{OVP}=1.0 \mathrm{~V}, \mathrm{R} 1=2.2 \mathrm{M} \Omega, \mathrm{R} 2=62 \mathrm{k} \Omega$
VOUT $=1.0 \times(2.2 \mathrm{M} \Omega+62 \mathrm{k} \Omega) / 62 \mathrm{k} \Omega=36.48 \mathrm{~V}$
(Example 4) VF=3.6V max, serial = 10 LED

$\mathrm{VOUT}=1.0 \times(1.0 \mathrm{M} \Omega+26.7 \mathrm{k} \Omega) / 26.7 \mathrm{k} \Omega=38.45 \mathrm{~V}$
5. The following shows how to confirm if LEDs are not turned on while selecting terminals. If the difference between the VF's total value of LED and over voltage is less than min. 10 V of LED terminal over voltage protect, LEDs should be turned on.

LEDs are turned on, as the following formula shows; $33.1 \mathrm{~V}-2.9 \mathrm{~V} \times 8$ serial $=9.9 \mathrm{~V}<10.0 \mathrm{~V}$.

- Over Current Limit

Over current flows the current detection resistor that is connected to internal switching transistor source and between PGND, Current sense voltage turns more than detection voltage decided with OCPSET, over current protection is operating and it is prevented from flowing more than detection current by reducing ON duty of switching Tr without stopping boost.
As over current detector of This IC is detected peak current, current more than over current setting value does not flow. And, over current value can decide freely by changing OCPSET voltage.

The range of over current setting is from 0.5 A to 2.5 A .
<Derivation sequence of detection resistor>
$R($ OCPSET $)=34 \mathrm{k} \Omega \times$ Over current setting


TYP value of over current is $2 \mathrm{~A}, \mathrm{MIN}=1.4 \mathrm{~A}$ and $\mathrm{MAX}=2.6 \mathrm{~A}$ and after the current value which was necessary for the normal operation was decided, detection resistor is derived by using MIN value of over current detection value.
For example, detection resistor when typ value was set at 2 A is given as shown below.
Detection resistor $=34 \mathrm{k} \Omega \times 2 \mathrm{~A}=68 \mathrm{k} \Omega$
MAX current dispersion of this detection resistor value is
MAX current $=2 \mathrm{~A} \times 1.3=2.6 \mathrm{~A}$
For example, $34 \mathrm{k} \Omega \rightarrow 1 \mathrm{~A}, 68 \mathrm{k} \Omega \rightarrow 2 \mathrm{~A}$
<The estimate of the current value which need for the normal operation >
As over current detector of This IC is detected the peak current, it have to estimate peak current to flow to the coil by operating condition.
In case of, o Supply voltage of coil = VIN ○ Inductance value of coil = L

- Switching frequency = fsw
- Output voltage = VOUT
$\mathrm{MIN}=1.0 \mathrm{MHz}$, Typ $=1.25 \mathrm{MHz}, \mathrm{MAX}=1.5 \mathrm{MHz}$
- Total LED current = IOUT
- Average current of coil = lave
- Efficiency = eff
- Peak current of coil = Ipeak
- ON time of switching transistor $=$ Ton

```
Ipeak = (VIN / L) > (1 / fsw) > (1-(VIN / VOUT))
lave=(VOUT × IOUT / VIN) / eff
Ton=(lave }\times(1-\textrm{VIN}/\mathrm{ VOUT ) }\times(1/fsw) \times(L/VIN) \times 2) 1/2
```

Each current is calculated.
As peak current varies according to whether there is the direct current superposed, the next is decided.

$$
\begin{array}{ll}
(1-\text { VIN } / \text { VOUT }) \times(1 / \text { fsw })<\text { Ton } \rightarrow & \text { peak current }=\text { Ipeak } / 2+\text { lave } \\
(1-\text { VIN } / \text { VOUT }) \times(1 / f s w)>\text { Ton } \rightarrow & \text { peak current }=(\text { VIN } / \text { L }) \times \text { Ton }
\end{array}
$$

## (Example 1)

In case of, $\mathrm{VIN}=6.0 \mathrm{~V}, \mathrm{~L}=4.7 \mu \mathrm{H}, \mathrm{fsw}=1.25 \mathrm{MHz}, \mathrm{VOUT}=39 \mathrm{~V}$, IOUT=80mA, Efficiency=85\%
Ipeak $=(6.0 \mathrm{~V} / 4.7 \mu \mathrm{H}) \times(1 / 1.25 \mathrm{MHz}) \times(1-(6.0 \mathrm{~V} / 39 \mathrm{~V}))=0.86 \mathrm{~A}$
lave $=(39 \mathrm{~V} \times 80 \mathrm{~mA} / 6.0 \mathrm{~V}) / 85 \%=0.61 \mathrm{~A}$
Ton $=(0.61 \mathrm{~A} \times(1-6.0 \mathrm{~V} / 39 \mathrm{~V}) \times(1 / 1.25 \mathrm{MHz}) \times(4.7 \mu \mathrm{H} / 6.0 \mathrm{~V}) \times 2)^{1 / 2}=0.81 \mu \mathrm{~s}$
$(1-\mathrm{VIN} / \mathrm{VOUT}) \times(1 / \mathrm{fsw})=0.68 \mu \mathrm{~s}<\mathrm{Ton}$
Peak current $=0.68 \mathrm{~A} / 2+0.61 \mathrm{~A}=1.04 \mathrm{~A}$

## (Example 2)

In case of, $\mathrm{VIN}=12.0 \mathrm{~V}, \mathrm{~L}=4.7 \mu \mathrm{H}, \mathrm{fsw}=1.25 \mathrm{MHz}, \mathrm{VOUT}=39 \mathrm{~V}$, $\mathrm{IOUT}=80 \mathrm{~mA}$, Efficiency=85\%
Ipeak $=(12.0 \mathrm{~V} / 4.7 \mu \mathrm{H}) \times(1 / 1.25 \mathrm{MHz}) \times(1-(12 \mathrm{~V} / 39 \mathrm{~V}))=1.41 \mathrm{~A}$
lave $=(39 \mathrm{~V} \times 80 \mathrm{~mA} / 12.0 \mathrm{~V}) / 85 \%=0.31 \mathrm{~A}$
Ton $=(0.31 \mathrm{~A} \times(1-12 \mathrm{~V} / 39 \mathrm{~V}) \times(1 / 1.25 \mathrm{MHz}) \times(4.7 \mu \mathrm{H} / 12 \mathrm{~V}) \times 2)^{1 / 2}=0.36 \mu \mathrm{~s}$
$(1-\mathrm{VIN} / \mathrm{VOUT}) \times(1 / \mathrm{fsw})=0.55 \mu \mathrm{~s}>$ Ton
Peak current $=12 \mathrm{~V} / 4.7 \mu \mathrm{H} \times 0.36 \mu \mathrm{~s}=0.92 \mathrm{~A}$

* When too large current is set, output overshoot is caused, be careful enough because it is led to break down of the IC in case of the worst.
- soft start of Over current limit for application

When the capacitor of OCPSET is set as figure, over current limit can become setting value slowly.
This effect is same as internal soft start.
When you want to reduce peak current than internal soft start on start up, this way is effective.
But, this action repeat when the timing that PWMPOW change $L$ to $H$, so to do PWM control with PWMPOW terminal, rise time of over current limit must be set into Hi time of PWM control, and please don't connect the capacitor.

Show example of rising wave form with OCPSET 330pF.


Fig. 25 Rising wave form with VBAT $=5 \mathrm{~V}$, 6 parallel 10 serial $20 \mathrm{~mA} / \mathrm{ch}$, OCPSET $=68 \mathrm{k} \Omega, 330 \mathrm{pF}$

## -Operating of the application deficiency

1) When 1 LED or 1 string OPEN during the operating

The LED string that became OPEN isn't lighting, but other LED strings are lighting.
Then LED terminal is 0 V , output boosts up to the over voltage protection voltage. When over voltage is detected, the feedback of open string isn't returned, so that VOUT will return normal voltage.
In the case that the voltage of 2 LED terminals becomes more than 25 V (Absolute maximum ratings) as VOUT boosts up to the over voltage protection voltage, please pay attention carefully that 2 LED terminals could be broken up in setting over voltage protection.

OVP setting when selecting terminals



Fig. 26 LED OPEN detect
Moreover, excessively high level of over voltage limit in terminal setting makes it happen that LED terminal voltage exceeds LED terminal over voltage protect, which accordingly turn off LED lights. In order to prevent this problem, please see "How to set the external resistor of over voltage limit ( $p .7$ )" and then set over voltage referring to application.
2) When LED short-circuited in the plural

All LED strings is turned on unless LED1~6 terminal voltage is more than 11.5 V .
When it was more than 11.5 V only the strings which short-circuited is turned off normally and LED current of other lines continue to turn on.


Fig. 27 LED short detect
3) When Schottky diode comes off

IC and a switching transistor aren't destroyed because boost operating stops by the Schottky diode coming off protected function.
4) When the resistor of over current detection comes off

All the LEDs do not turn on due to open protect of the OVP resistor, which stops boost operation and consequently prevents passing LED current.

## - How to activate

Please pay attention to the following when activating.

1. The lights are turned off by LED terminal over voltage protection in the case that LED terminal voltage is more than $11.5 \mathrm{~V}(\mathrm{typ})$ at PWMDRV=H. LED terminal becomes more than 11.5 V depending on OVP setting. In that case, please refer to how to set on P7.
2. In the case that capacitors are placed between anode and casode, LED terminal might become more than 11.5 V depending on power supply activating time. Please make t 12 in Fig. 28 long enough until LED terminal becomes less than 11.5 V . or use application.
3. If PWMPOW and PWMDRV terminal voltage become more than VBAT voltage in the case that activation of power supply voltage (VBAT) is not completely finished, error might be occurred by supplying power supply into VBAT via ESD protection diode on the VBAT side of each terminal.

Fig. 28 shows input timing of VBAT, PWMPOW, and PWMDRV. Please input signal paying attention to the above. In the case that conditions are not good enough, it happens that lights are turned off at activation.

Terminal select circuit inside IC operates using VREG as power supply. In the case that VREG does not activate (less than UVLO), please set PWMDRV=H t12 hours after setting PWMPOW=H. Terminal select circuit is reset by PWMDRV=L signal while VREG rises after PWMPOW=L->H. Lights might be turned off unless PWMDRV=L is input until VREG becomes stable at activation. After activation, VREG voltage is more than UVLO, reset is not needed since terminal information is saved.

At light dimming of PWMDRV terminal


At light dimming of PWMPOW terminal


Fig. 28 input timing

|  | Name | Unit | Min. | Typ. | Max. |
| :---: | :--- | :---: | :---: | :---: | :---: |
| t 1 | Power supply activating time | $\mu \mathrm{s}$ | 100 | - | - |
| t 2 | Power supply-PWMPOW time | $\mu \mathrm{s}$ | 0 | - | - |
| t 3 | PWMPOW rising time | $\mu \mathrm{s}$ | 0 | - | 100 |
| t4 | PWMPOW falling time | $\mu \mathrm{s}$ | 0 | - | 100 |
| t5 | PWMPOW low time | $\mu \mathrm{s}$ | 50 | - | - |
| t6 | Power supply-PWMDRV time | $\mu \mathrm{s}$ | 1600 | - | - |
| t7 | PWMDRV rising time | $\mu \mathrm{s}$ | 0 | - | 100 |
| t8 | PWMDRV high time | $\mu \mathrm{s}$ | 5 | - | - |
| t9 | PWMDRV falling time | $\mu \mathrm{s}$ | 0 | - | 100 |
| t10 | PWMDRV low time | $\mu \mathrm{s}$ | 5 | - | - |
| t11 | PWMDRV cycle | $\mu \mathrm{s}$ | 40 | 5000 | 10000 |
| t12 | PWMPOW cycle | $\mu \mathrm{s}$ | 1000 | 5000 | 10000 |
| t13 | PWMPOW high time | $\mu \mathrm{s}$ | 50 | - | - |
| t14 | PWMPOW(H)->PWMDRV(H) time | $\mu \mathrm{s}$ | 1500 | - | - |
| t15 | PWMPOW(L)->PWMDRV(L) time | $\mu \mathrm{s}$ | 0 | - | - |
| t16 | PWMDRV(L)->PWMPOW(L) time | $\mu \mathrm{s}$ | 0 | - | - |
| H | Operation Voltage | $V$ | 4.2 | 12 | 26 |
| L | Non operation voltage | $V$ | - | - | 4.2 |



Fig. 29 Example of application at control signal voltage > VBAT voltage

## - Start control (PWMPOW) and select LED current driver (PWMDRV)

This IC can control the IC system by PWMPOW, and IC can power off compulsory by setting 0.9 V or below. Also, It powers on PWMPOW is at more than 2.1 V .
After it's selected to PWMPOW=H, When it is selected at PWMDRV=H, LED current decided with ISET resistance flow. Next, When it is selected at PWMDRV=L, LED current stop to flow.

| PWMPOW | PWMDRV | IC | LED current |
| :---: | :---: | :---: | :--- |
| L | L | Off | OFF |
| H | L | On | OFF |
| L | H | Off | OFF |
| H | H | On | Current decided with ISET |

## -How to select the number of LED lines of the current driver

When the number of LED lines of the current driver is reduced, the un-select can be available by setting the unnecessary LED1~6 terminals OPEN. In the case of using 4 lines and so on, please connect the unnecessary 2 lines OPEN.

Then please set PWMPOW and PWMDRV "H" and finish selecting the lines within the process of softstart. If the level of over voltage limit is set too high, the connected LED lines exceed LED terminal over voltage protect and are judged as unnecessary lines.
Please make it sure referring "How to set over voltage limit (p.7)".
Additionally, once the terminals are judged as unnecessary, this information never can be reset without setting PWMPOW and PWMDRV " L ".

## -LED current setting range

LED current can set up Normal current by resistance value (RISET) connecting to ISET voltage.
Setting of each LED current is given as shown below.
Normal current $=16 \mathrm{~mA}(27 \mathrm{k} \Omega /$ RISET $)$
Also, Normal current setting range is $10 \mathrm{~mA} \sim 30 \mathrm{~mA}$. LED current becomes a leak current MAX $2 \mu \mathrm{~A}$ at OFF setting. When using beyond current setting range, please be careful that the error in LED current setting could be large.
ISET Normal current setting example

| RISET | LED current |
| :---: | :---: |
| $18 \mathrm{k} \Omega(E 24)$ | 24.0 mA |
| $22 \mathrm{k} \Omega(E 24)$ | 19.6 mA |
| $24 \mathrm{k} \Omega(E 24)$ | 18.0 mA |
| $27 \mathrm{k} \Omega(E 24)$ | 16.0 mA |
| $30 \mathrm{k} \Omega(E 24)$ | 14.4 mA |
| $33 \mathrm{k} \Omega(E 24)$ | 13.1 mA |

## - Brightness control

There are two dimming method is available, first method is analog dimming that apply analog voltage to ISET terminal, and second method is PWM control via digital dimming of PWMPOW or PWMDRV. Because each method has the different merit, please choose a suitable method for the application of use.
Two techniques can be used as digital dimming by the PWM control One is PWM control of current driver, the other is PWM control of power control.
As these two characteristics are shown in the below, selects to PWM control process comply with application.

- Efficiency emphasis in the low brightness which has an influence with the battery life
$\rightarrow$ 2) Power control PWM control
- LED current dispersion emphasis in the PWM brightness control
$\rightarrow$ 1) Current driver PWM control
(Reference)

| PWM regulation process | Efficiency of LED current 0.5mA <br> (PWM Duty=2.5\%) | PWM frequency 200Hz <br> Limit dispersion capability of low duty |
| :---: | :---: | :---: |
| Current driver | $74.8 \%$ | $0.04 \%$ |
| Power control | $91 \%$ | $0.40 \%$ |

1) Current driver PWM control is controlled by providing PWM signal to PWMDRV, as it is shown Fig. 30 .

The current set up with ISET is chosen as the H section of PWMDRV and the current is off as the L section. Therefore, the average LED current is increasing in proportion to duty cycle of PWMDRV signal. This method that it lets internal circuit and DC/DC to work, because it becomes to switch the driver, the current tolerance is a few when the PWM brightness is adjusted, so it makes it possible to brightness control until $5 \mu \mathrm{~s}$ ( $\mathrm{MINO} .1 \%$ at 200 Hz ). And, don't use for the brightness control, because effect of ISET changeover is big under $1 \mu \mathrm{~s}$ ON time and under $1 \mu \mathrm{~s}$ OFF time. Typical PWM frequency is $100 \mathrm{~Hz} \sim 25 \mathrm{kHz}$.

2) Power control PWM control is controlled by providing PWM signal to PWMPOW, as it is shown Fig.31. The current setting set up with PWMDRV logic is chosen as the H section and the current is off as the L section. Therefore, the average LED current is increasing in proportion to duty cycle of PWMPOW signal. This method is, because IC can be power-off at off-time, the consumption current can be suppress, and the high efficiency can be available, so it makes it possible to brightness control until $50 \mu \mathrm{~s}$ ( $\mathrm{MIN} 1 \%$ at 200 Hz ). And, don't use for the brightness control, because effect of power ON/OFF time changeover is big under $50 \mu$ s ON time and under $50 \mu$ s OFF time. Typical PWM frequency is $100 \mathrm{~Hz} \sim 1 \mathrm{kHz}$.


Fig. 31 PWMPOW sequence

## - Output voltage ripple for PWM dimming

Conditio: 8serial 6 parallel, LED current $=20 \mathrm{~mA} / \mathrm{ch}, \mathrm{VBAT}=7 \mathrm{~V}, \mathrm{Ta}=25^{\circ} \mathrm{C}$, output capacitor $=2.2 \mu \mathrm{~F}(50 \mathrm{~V} / \mathrm{B} 3)$


Fig. 32 Output voltage ripple for PWM dimming

## -LED current rise and fall for PWM dimming

Conditions : 8serial 6 parallel, LED current $=20 \mathrm{~mA} / \mathrm{ch}, \mathrm{VBAT}=7 \mathrm{~V}, \mathrm{Ta}=25^{\circ} \mathrm{C}$, output capacitor $=2.2 \mu \mathrm{~F}(50 \mathrm{~V} / \mathrm{B} 3)$


Fig. 33 PWM characteristics of current driver PWM



Fig. 34 PWM characteristics of power control PWM

## - Main characteristics of efficiency

Conditions:
10serial 6 parallel, LED current $=20 \mathrm{~mA} / \mathrm{ch}$, output capacitor $=2.2 \mu \mathrm{~F}(50 \mathrm{~V} / \mathrm{B} 3)$



Fig. 35 Efficiency of current driver PWM


Fig. 36 Efficiency of power control PWM

## - The coil selection

The DC/DC is designed by more than $4.7 \mu \mathrm{H}$. When L value sets to a lower value, it is possibility that the specific sub-harmonic oscillation of current mode DC / DC will be happened.
Please do not let L value to $3.3 \mu \mathrm{H}$ or below.
And, $L$ value increases, the phase margin of DC / DC becomes to zero. Please enlarge the output capacitor value when you increase $L$ value.

Example)

| $4.7 \mu \mathrm{H}$ | $=$ | output capacitor | $2.2 \mu \mathrm{~F} / 50 \mathrm{~V}$ |
| :--- | :--- | :--- | :--- |
| $6.8 \mu \mathrm{H}$ | $=$ | output capacitor | $2.2 \mu \mathrm{~F} / 50 \mathrm{~V}$ |
| $10 \mu \mathrm{H}$ | $=$ | output capacitor | $2.2 \mu \mathrm{~F} / 50 \mathrm{~V}$ |
|  |  |  | 3 pcs |

This value is just examples, please made sure the final judgment is under an enough evaluation.
-The separation of the IC power supply and coil power supply
This IC can work in separating the power source in both IC power supply and coil power supply. With this application, it can obtain that decrease of IC power consumption, and the applied voltage exceeds IC rating 26 V .

That application is shown in below Fig.14. The higher voltage source is applied to the power source of coil that is connected from 4.2 V to 5.5 V into IC VBAT, please follow the recommend design in Fig.14. It connects VBAT terminal and VREG terminal together at IC outside.

When the coil power supply is applied, it is no any problem even though IC power supply is the state of OV. Although IC power supply is set to 0 V , pull-down resistance is arranged for the power off which cuts off the leak route from coil power supply in IC inside, the leak route is cut off. And, there is no power on-off sequence of coil power supply and IC power supply.


Fig. 37 Application at the time of power supply isolation (6parallel)

## - Selection of external parts

Recommended external parts are as shown below.
When to use other parts than these, select the following equivalent parts.

- Coil

| Value | Manufacturer | Product number | Size |  |  | $\begin{gathered} \text { DC current } \\ (\mathrm{mA}) \end{gathered}$ | $\begin{gathered} \text { DCR } \\ (\Omega) \end{gathered}$ |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  | Vertical | Horizontal | Height (MAX) |  |  |
| $4.7 \mu \mathrm{H}$ | TOKO | A915AY-4R7M | 5.2 | 5.2 | 3.0 | 1870 | 0.045 |
| $4.7 \mu \mathrm{H}$ | TOKO | B1015AS-4R7M | 8.4 | 8.3 | 4.0 | 3300 | 0.038 |
| $4.7 \mu \mathrm{H}$ | TDK | LTF5022T-4R7N2R0-LC | 5.0 | 5.2 | 2.2 | 2000 | 0.073 |
| $10 \mu \mathrm{H}$ | TOKO | A915AY-100M | 5.2 | 5.2 | 3.0 | 1870 | 0.090 |
| $10 \mu \mathrm{H}$ | TDK | LTF5022T-100M1R4-LC | 5.0 | 5.2 | 2.2 | 1400 | 0.140 |

- Capacitor

| Value | Pressure | Manufacturer | Product number | Size |  |  | TC | Capa Tolerance |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | Vertical | Horizontal | Height |  |  |
| [ Supply voltage capacitor] |  |  |  |  |  |  |  |  |
| $2.2 \mu \mathrm{~F}$ | 10 V | MURATA | GRM188B31A225K | 1.6 | 0.8 | $0.8 \pm 0.1$ | B | +/-10\% |
| $4.7 \mu \mathrm{~F}$ | 25 V | MURATA | GRM319R61E475K | 3.2 | 1.6 | $0.85 \pm 0.1$ | X5R | +/-10\% |
| $4.7 \mu \mathrm{~F}$ | 25V | MURATA | GRM21BR61E475K | 2.0 | 1.25 | $1.25 \pm 0.1$ | X5R | +/-10\% |
| 10رF | 25 V | MURATA | GRM31CB31E106K | 3.2 | 1.6 | $1.6 \pm 0.2$ | B | +/-10\% |
| 10ヶF | 10 V | MURATA | GRM219R61A106K | 2.0 | 1.25 | $0.85 \pm 0.15$ | X5R | +/-10\% |
| [ Smoothing capacitor for built-in regulator ] |  |  |  |  |  |  |  |  |
| $1 \mu \mathrm{~F}$ | 10V | MURATA | GRM188B10J105K | 1.6 | 0.8 | $0.8 \pm 0.1$ | B | +/-10\% |
| $4.7 \mu \mathrm{~F}$ | 10 V | MURATA | GRM219B31A475K | 2.0 | 1.25 | $0.85 \pm 0.1$ | B | +/-10\% |
| [ Output capacitor] |  |  |  |  |  |  |  |  |
| $1 \mu \mathrm{~F}$ | 50 V | MURATA | GRM31MB31H105K | 3.2 | 1.6 | $1.15 \pm 0.1$ | B | +/-10\% |
| $1 \mu \mathrm{~F}$ | 50 V | MURATA | GRM21BB31H105K | 2.0 | 1.25 | $1.25 \pm 0.1$ | B | +/-10\% |
| $2.2 \mu \mathrm{~F}$ | 50 V | TDK | C3225JB1H225K | 3.2 | 2.5 | $2.0 \pm 0.2$ | B | +/-10\% |
| $2.2 \mu \mathrm{~F}$ | 50 V | MURATA | GRM31CB31H225K | 3.2 | 1.6 | $1.6 \pm 0.2$ | B | +/-10\% |
| $0.33 \mu \mathrm{~F}$ | 50 V | MURATA | GRM219B31H334K | 2.0 | 1.25 | $0.85 \pm 0.1$ | B | +/-10\% |

- Resistor

| Value | Tolerance | Manufacturer | Product number | Size |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | Horizontal | Height |  |
| $10 \mathrm{k} \Omega$ | $\pm 0.5 \%$ | ROHM | MCR03EZPD1002 | 1.6 | 0.8 | 0.45 |
| $15 \mathrm{k} \Omega$ | $\pm 0.5 \%$ | ROHM | MCR03EZPD1502 | 1.6 | 0.8 | 0.45 |
| $18 \mathrm{k} \Omega$ | $\pm 0.5 \%$ | ROHM | MCR03EZPD1802 | 1.6 | 0.8 | 0.45 |
| $22 \mathrm{k} \Omega$ | $\pm 0.5 \%$ | ROHM | MCR03EZPD2202 | 1.6 | 0.8 | 0.45 |
| $24 \mathrm{k} \Omega$ | $\pm 0.5 \%$ | ROHM | MCR03EZPD2402 | 1.6 | 0.8 | 0.45 |
| $27 \mathrm{k} \Omega$ | $\pm 0.5 \%$ | ROHM | MCR03EZPD2702 | 1.6 | 0.8 | 0.45 |
| $30 \mathrm{k} \Omega$ | $\pm 0.5 \%$ | ROHM | MCR03EZPD3002 | 1.6 | 0.8 | 0.45 |
| $33 \mathrm{k} \Omega$ | $\pm 0.5 \%$ | ROHM | MCR03EZPD3302 | 1.6 | 0.8 | 0.45 |
| $56 \mathrm{k} \Omega$ | $\pm 0.5 \%$ | ROHM | MCR03EZPD5602 | 1.6 | 0.8 | 0.45 |
| $62 \mathrm{k} \Omega$ | $\pm 0.5 \%$ | ROHM | MCR03EZPD6202 | 1.6 | 0.8 | 0.45 |
| $68 \mathrm{k} \Omega$ | $\pm 0.5 \%$ | ROHM | MCR03EZPD6802 | 1.6 | 0.8 | 0.45 |
| $75 \mathrm{k} \Omega$ | $\pm 0.5 \%$ | ROHM | MCR03EZPD7502 | 1.6 | 0.8 | 0.45 |
| $2.2 \mathrm{M} \Omega$ | $\pm 0.5 \%$ | ROHM | MCR03EZPD2204 | 1.6 | 0.8 | 0.45 |

- SBD

| Pressure | Manufacturer | Product number | Size |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  | Vertical | Horizontal | Height |
| 60 V | ROHM | RB160M-60 | 3.5 | 1.6 | 0.8 |

The coil is the part that is most influential to efficiency. Select the coil whose direct current resistor (DCR) and current inductance characteristic is excellent. BD6xxx is designed for the inductance value of $4.7 \mu \mathrm{H}$. Don't use the inductance value. less than $3.3 \mu \mathrm{H}$. Select a capacitor of ceramic type with excellent frequency and temperature characteristics.
Further, select Capacitor to be used with small direct current resistance, and pay sufficient attention to the PCB layout.

## - PCB Layout

In order to make the most of the performance of this IC, its PCB layout is very important. Characteristics such as efficiency and ripple and the likes change greatly with layout patterns, which please note carefully.


Fig. 38 PCB Layout
<Input capacitor CVL1 ( $10 \mu \mathrm{~F}$ ) for coil>
Connect input capacitor CVL1 $(10 \mu \mathrm{~F})$ as close as possible between coil L1 and PGND.
<Input bypath capacitor CVB1 ( $1 \mu \mathrm{~F}$ ) for IC>
Put input bypath capacitor CVB1 ( $1 \mu \mathrm{~F}$ ) as close as possible between VBAT and PGND pin.
<Smoothing capacitor CVR3(2.2uF) of the regulator>
Connect smoothing capacitor CVR3 $(2.2 \mu \mathrm{~F})$ as close as possible between VREG pin and PGND.
<Schottky barrier diode SBD>
Connect schottky barrier diode SBD as close as possible between coil1and SW pin.
<Output capacitor CO1>
Connect output capacitor CO1 between cathode of SBD and PGND.
Make both PGND sides of CVL1 and CO1 as close as possible.
<LED current setting resistor RISET(22k 2 )>>
Connect LED current setting resistor RISET $(22 \mathrm{k} \Omega$ ) as close as possible between ISET pin and GND.
There is possibility to oscillate when capacity is added to ISET terminal, so pay attention that capacity isn't added.
<Over current limit setting resistor ROC(68k $\Omega$ )>
Connect Over current limit setting resistor ROC(68k $\Omega$ ) as close as possible between OCPSET pin and GND.
< Over current limit setting resistor RVT(2.2M $\Omega$ ) \& RVD ( $56 \mathrm{k} \Omega$ )>
Put over current limit setting resistor $\operatorname{RVT}(2.2 \mathrm{M} \Omega)$ \& $\operatorname{RVD}(56 \mathrm{k} \Omega$ ) as close as possible VDET pin so as not to make the wire longer, which possibly causes the noise and also detects over voltage protection by mistake.
<Connect to GND and PGND>
GND is analog ground, and PGND is power ground. PGND might cause a lot of noise due to the coil current of PGND. Try to connect with analog ground, after smoothing with input capacitor CVL1 and output capacitor CO1.
<Heat radiation of back side PAD>
PAD is used for improving the efficiency of IC heat radiation. Solder PAD to GND pin (analog ground).
Moreover, connect ground plane of board using via as shown in the patterns of next page.
The efficiency of heat radiation improves according to the area of ground plane.
<Others>
When those pins are not connected directly near the chip, influence is give to the performance of BD6150, and may limit the current drive performance. As for the wire to the inductor, make its resistance component small so as to reduce electric power consumption and increase the entire efficiency.
The layout pattern in consideration of these is shown in the next page.

## - Recommended PCB layout pattern



Top Layer


Mid layer 1


Mid layer 2


Bottom layer
Fig. 39 PCB layout patterns

## - About heat loss

In heat design, operate the DC/DC converter in the following condition.
(The following temperature is a guarantee temperature, so consider the margin.)

1. Ambient temperature Ta must be less than $85^{\circ} \mathrm{C}$.
2. The loss of IC must be less than dissipation Pd.

## -Application example

- LED current setting controlled ISETH resistor.
$21.5 \mathrm{k} \Omega$ : 20.1 mA
$27.0 \mathrm{k} \Omega$ : 16.0 mA
$14.7 \mathrm{k} \Omega: 29.59 \mathrm{~mA}$
- Brightness control

Please input PWM pulse from PWMPOW or PWMDRV terminal.
Please refer electrical characteristics p. 3 and function (p.12).

## 15inch panel



Fig. 4010 series $\times 6$ parallel, LED current 16 mA setting
Switching frequency 750 kHz setting example
Power control PWM application


Fig. 4210 series $\times 6$ parallel, LED current 16 mA setting Switching frequency 750 kHz setting example Current driver PWM application


Fig. 4110 series $\times 6$ parallel, LED current 16 mA , Switching frequency 1250 kHz example Power control PWM application


Fig. 4310 series $\times 6$ parallel, LED current 16 mA setting Switching frequency 1250 kHz setting example Current driver PWM application


Fig. 44 8series $\times 6$ paralell LED current 16 mA setting, Switching frequency 1250 kHz setting example Power control PWM application


Fig. 45 8series $\times 6$ paralell, LED current 16 mA setting, Switching frequency 1250 kHz setting example Current driver PWM application

10~12inch pane


Fig. 467 series $\times 6$ parallel, LED current 16 mA setting, Switching frequency 1250 kHz setting example Power control PWM application

## 7inch pane



Fig. 47 8series $\times 3$ parallel, LED current 16 mA setting, Switching frequency 1250 kHz setting example Power control PWM application


Fig. 49 8series $\times 3$ parallel, LED current 40.2 mA setting, Switching frequency 1250 kHz setting example Power control PWM application

Fig. 48 sseries $\times 4$ parallel, LED current 16 mA setting,
Switching frequency 1250 kHz setting example Power control PWM application


5inch pane


Fig. 50 8series $\times 2$ parallel, LED current 16 mA setting,
Switching frequency 1250 kHz setting example Power control PWM application


Fig. 51 8series $\times 2$ parallel, LED current 40.2 mA setting,
Switching frequency 1250 kHz setting example Power control PWM application


Fig. 52 8series $\times 2$ parallel, LED current 88.8 mA setting,
Switching frequency 1250 kHz setting example
Power control PWM application


Fig. 53 3series $\times 5$ parallel, LED current 16 mA setting, Switching frequency 1250 kHz setting example Power control PWM application


Fig. 55 3series $\times 6$ parallel, LED current 177.6 mA setting, Switching frequency 1250 kHz setting example Power control PWM application


Fig. 54 3series $\times 6$ parallel, LED current 29.6 mA setting, Switching frequency 1250 kHz setting example Power control PWM application


Fig. 56 10series $\times 1$ parallel, LED current 177.6 mA setting, Switching frequency 1250 kHz setting example Power control PWM application

## - Application example of Analog dimming

Control LED current to charged D/A voltage.
Show application example and typ control.
Please decide final value after you evaluated application, characteristic.


Fig. 57 BD6150 Analog style optical application

$$
\begin{aligned}
& \text { LEDcurrent }=\frac{432}{470 \mathrm{k} \Omega}+\frac{432}{22 \mathrm{k} \Omega}\left(1-\frac{\mathrm{DAC}}{\text { ISETvoltage }}\right) \\
& \text { typ LEDcurrent }=\frac{432}{470 \mathrm{k} \Omega}+\frac{432}{22 \mathrm{k} \Omega}\left(1-\frac{\mathrm{DAC}}{0.6 \mathrm{~V}}\right)
\end{aligned}
$$

## - Notes for use

(1) Absolute Maximum Ratings

An excess in the absolute maximum ratings, such as supply voltage, temperature range of operating conditions, etc., can break down devices, thus making impossible to identify breaking mode such as a short circuit or an open circuit. If any special mode exceeding the absolute maximum ratings is assumed, consideration should be given to take physical safety measures including the use of fuses, etc.
(2) Operating conditions

These conditions represent a range within which characteristics can be provided approximately as expected. The electrical characteristics are guaranteed under the conditions of each parameter.
(3) Reverse connection of power supply connector

The reverse connection of power supply connector can break down ICs. Take protective measures against the breakdown due to the reverse connection, such as mounting an external diode between the power supply and the IC's power supply terminal.
(4) Power supply line

Design PCB pattern to provide low impedance for the wiring between the power supply and the GND lines. In this regard, for the digital block power supply and the analog block power supply, even though these power supplies has the same level of potential, separate the power supply pattern for the digital block from that for the analog block, thus suppressing the diffraction of digital noises to the analog block power supply resulting from impedance common to the wiring patterns. For the GND line, give consideration to design the patterns in a similar manner.
Furthermore, for all power supply terminals to ICs, mount a capacitor between the power supply and the GND terminal. At the same time, in order to use an electrolytic capacitor, thoroughly check to be sure the characteristics of the capacitor to be used present no problem including the occurrence of capacity dropout at a low temperature, thus determining the constant.
(5) GND voltage

Make setting of the potential of the GND terminal so that it will be maintained at the minimum in any operating state. Furthermore, check to be sure no terminals are at a potential lower than the GND voltage including an actual electric transient.
(6) Short circuit between terminals and erroneous mounting

In order to mount ICs on a set PCB, pay thorough attention to the direction and offset of the ICs. Erroneous mounting can break down the ICs. Furthermore, if a short circuit occurs due to foreign matters entering between terminals or between the terminal and the power supply or the GND terminal, the ICs can break down.
(7) Operation in strong electromagnetic field

Be noted that using ICs in the strong electromagnetic field can malfunction them.
(8) Inspection with set PCB

On the inspection with the set PCB, if a capacitor is connected to a low-impedance IC terminal, the IC can suffer stress. Therefore, be sure to discharge from the set PCB by each process. Furthermore, in order to mount or dismount the set PCB to/from the jig for the inspection process, be sure to turn OFF the power supply and then mount the set PCB to the jig. After the completion of the inspection, be sure to turn OFF the power supply and then dismount it from the jig. In addition, for protection against static electricity, establish a ground for the assembly process and pay thorough attention to the transportation and the storage of the set PCB.
(9) Input terminals

In terms of the construction of IC, parasitic elements are inevitably formed in relation to potential. The operation of the parasitic element can cause interference with circuit operation, thus resulting in a malfunction and then breakdown of the input terminal. Therefore, pay thorough attention not to handle the input terminals, such as to apply to the input terminals a voltage lower than the GND respectively, so that any parasitic element will operate. Furthermore, do not apply a voltage to the input terminals when no power supply voltage is applied to the IC. In addition, even if the power supply voltage is applied, apply to the input terminals a voltage lower than the power supply voltage or within the guaranteed value of electrical characteristics.
(10) Ground wiring pattern

If small-signal GND and large-current GND are provided, It will be recommended to separate the large-current GND pattern from the small-signal GND pattern and establish a single ground at the reference point of the set PCB so that resistance to the wiring pattern and voltage fluctuations due to a large current will cause no fluctuations in voltages of the small-signal GND. Pay attention not to cause fluctuations in the GND wiring pattern of external parts as well.
(11) External capacitor

In order to use a ceramic capacitor as the external capacitor, determine the constant with consideration given to a degradation in the nominal capacitance due to DC bias and changes in the capacitance due to temperature, etc.
(12) Thermal shutdown circuit (TSD)

When junction temperatures become $175^{\circ} \mathrm{C}$ (typ) or higher, the thermal shutdown circuit operates and turns a switch OFF. The thermal shutdown circuit, which is aimed at isolating the LSI from thermal runaway as much as possible, is not aimed at the protection or guarantee of the LSI. Therefore, do not continuously use the LSI with this circuit operating or use the LSI assuming its operation.
(13) Thermal design

Perform thermal design in which there are adequate margins by taking into account the permissible dissipation (Pd) in actual states of use.
(14) Selection of coil

Select the low DCR inductors to decrease power loss for DC/DC converter.

## - Ordering part number


Part No.
6150

Package
MUV: VQFN024V4040

Packaging and forming specification E2: Embossed tape and reel

VQFN024V4040



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[^0]:    *1 Reduced $4.0 \mathrm{~mW} /{ }^{\circ} \mathrm{C}$ With $\mathrm{Ta}>25^{\circ} \mathrm{C}$ when not mounted on a heat radiation Board.
    *2 1 layer (ROHM Standard board) has been mounted. Copper foil area $0 \mathrm{~mm}^{2}$, When it's used by more than $\mathrm{Ta}=25^{\circ} \mathrm{C}$, it's reduced by $6.2 \mathrm{~mW} /{ }^{\circ} \mathrm{C}$.
    *3 4 layer (JEDEC Compliant board) has been mounted. Copper foil area 1 layer $6.28 \mathrm{~mm}^{2}$, Copper foil area 2~4layers $5655.04 \mathrm{~mm}^{2}$,
    When it's used by more than $\mathrm{Ta}=25^{\circ} \mathrm{C}$, it's reduced by $12.1 \mathrm{~mW} /{ }^{\circ} \mathrm{C}$.

[^1]:    *1 This parameter is tested with DC measurement.

